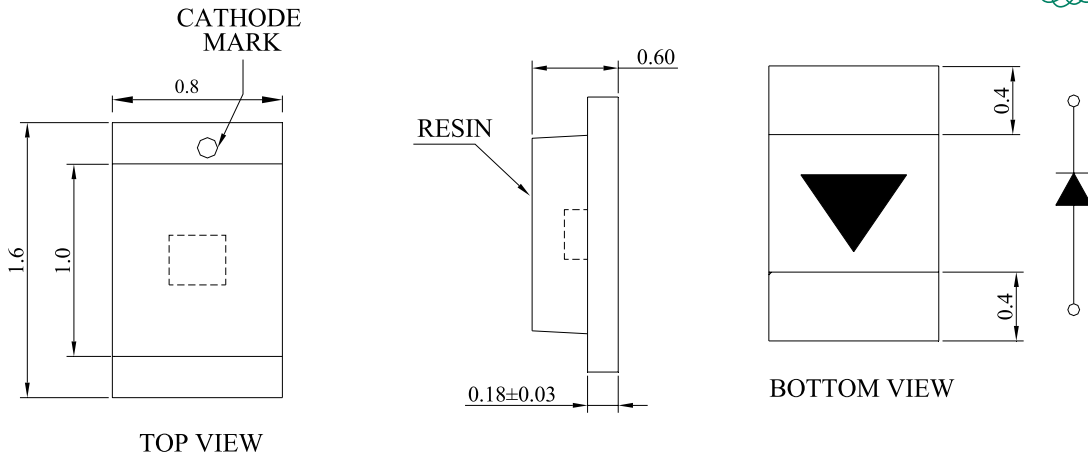


SMD Chip LED



Package Dimensions:



All dimensions are in mm
Tolerance: ±0.1mm

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	P _D	78	°C
Reverse Voltage	V _R	5	V
D.C. Forward Current	I _f	30	mA
Pulsed Forward Current (1 / 10 Duty Cycle, 0.1ms Pulse Width)	I _f (Peak)	80	mA
Operating Temperature Range	T _{opr.}	-40 to +80	°C
Storage Temperature Range	T _{stg.}	-40 to +85	°C
Soldering Temperature	T _{sld.}	Reflow Soldering: 260°C for 10sec.	

Electrical & Optical Characteristics: Hyper Red

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _f = 20mA	-	11	-	mcd
Forward Voltage	V _f	I _f = 20mA	1.9	-	2.6	V
Peak Wavelength	λ _p	I _f = 20mA	-	567	-	nm
Dominant Wavelength	λ _d	I _f = 20mA	-	572	-	nm
Reverse Current	I _r	V _r = 5V	-	-	100	μA
Viewing Angle	2θ ½	I _f = 20mA	-	140	-	deg
Spectrum Line Halfwidth	Δλ	I _f = 20mA	-	30	-	nm

Note: 1. The data is tested by an IS tester
2. Customer's special requirements are also welcome.

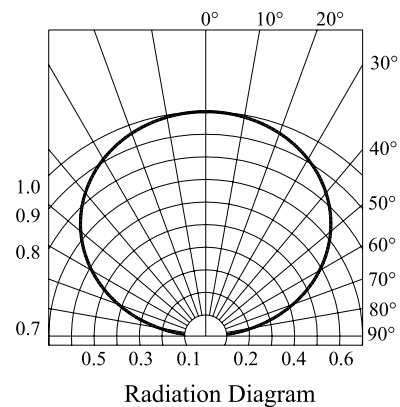
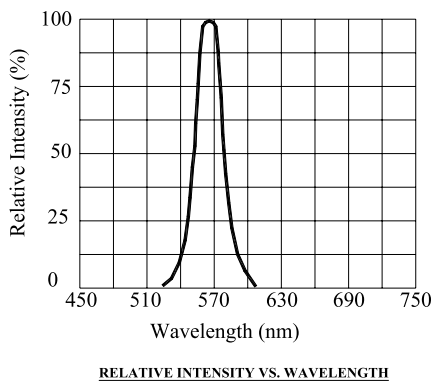
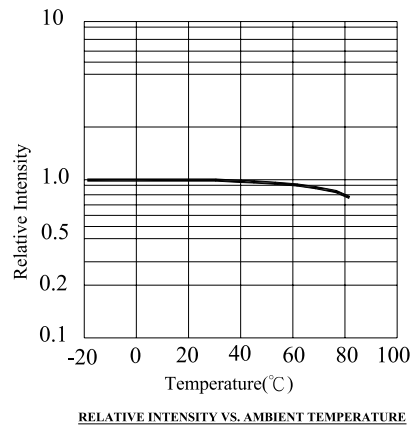
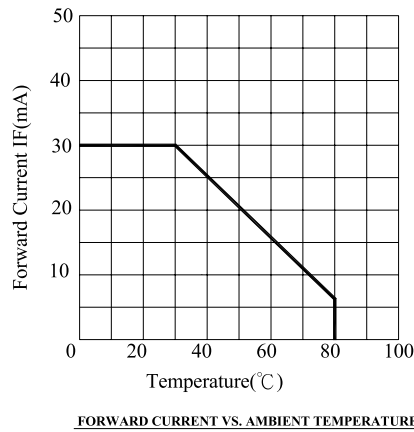
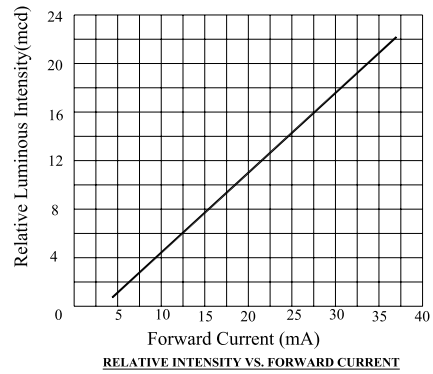
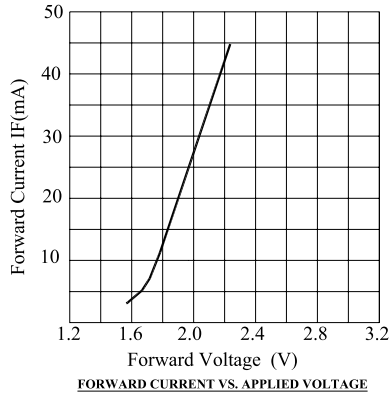


SMD Chip LED



Typical Electrical & Optical Characteristics Curves:

(25°C Ambient temperature unless otherwise noted)



Recommended Storage Environment:

- Temperature: 5°C to 30°C (41°F to 86°F)
- Humidity: 60% RH Max.
- Use within 7 days after opening of sealed vapour/ESD barrier bags

If moisture absorbent material (silica gel) has faded away or LEDs have exceeded the storage time, baking treatment should be performed using the following conditions:

- Baking Treatment : 60 ± 5°C for 24 hours
- Fold the opened bag firmly and keep in dry environment

Reflow Soldering

Recommended use of upper and lower heater type reflow furnace.

- 260°C max for up to 10 seconds, one time only
- Pre-heat is 150°C max for up to 2 minutes max
- In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm

Cleaning

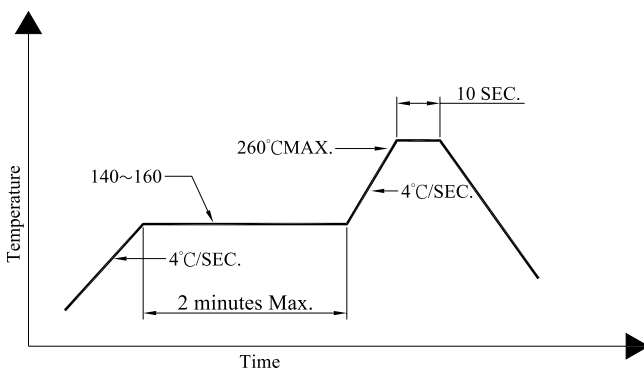
Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

- Avoid using organic solvent
- Recommend ultrasonic method 300W max.

Packaging

- EIA-481A standard package
- In 8mm tape on 4,000pcs diameter reels sealed in vapour/ESD barrier bags

Reflow Temp / Time:



Part Number Table

LED Chip		Lens Colour	Part Number
Material	Emitting Colour		
GaP / GaP	Green	White diffused	703-0109

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